

PCN Number: 20150602000 **PCN Date:** 06/05/2015

Title: Assembly Site move from Amkor K1 to TI Melaka for DP83846AVHG/NOPB Device

Customer Contact: [PCN Manager](#) **Dept:** Quality Services

Proposed 1st Ship Date: 09/05/2015 **Estimated Sample Availability:** Date provided at sample request

| Change Type: | | |
|-------------------------------------|---------------------------|--|
| <input checked="" type="checkbox"/> | Assembly Site | <input type="checkbox"/> Design |
| <input type="checkbox"/> | Assembly Process | <input type="checkbox"/> Data Sheet |
| <input checked="" type="checkbox"/> | Assembly Materials | <input type="checkbox"/> Part number change |
| <input type="checkbox"/> | Mechanical Specification | <input type="checkbox"/> Test Site |
| <input checked="" type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> Test Process |
| | | <input type="checkbox"/> Wafer Bump Site |
| | | <input type="checkbox"/> Wafer Bump Material |
| | | <input type="checkbox"/> Wafer Bump Process |
| | | <input type="checkbox"/> Wafer Fab Site |
| | | <input type="checkbox"/> Wafer Fab Materials |
| | | <input type="checkbox"/> Wafer Fab Process |

PCN Details

Description of Change:

Assembly Site move from Amkor K1 to TI Melaka for Select Device. No material differences between sites.

Reason for Change:

Closure of the Amkor K1 assembly facility. Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None.

Changes to product identification resulting from this PCN:

Sample Product Shipping Label (not actual product label)

Group 1: Assembly Site

| | | |
|-------------------|----------------------------|----------|
| Amkor K1 | Assembly Site Origin (22L) | ASO: AMN |
| TI Melaka (TIEMA) | Assembly Site Origin (22L) | ASO: GNZ |



MADE IN: Malaysia
2DC: 2Q:

| | |
|--------------------|----------|
| MSL 2 /260C/1 YEAR | SEAL DT |
| MSL 1 /235C/UNLIM | 03/29/04 |

OPT:
ITEM: 39
LBL: 5A (L)T0:1750





(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

ASSEMBLY SITE CODES: AMKOR K1 =7, TIEMA = 1

Product Affected Group:

DP83846AVHG/NOPB

Qualification Report

Amkor K1 Closure and L/TQFP transfer to TIEMA

Product Description

| Part Number | Process | Package / # Leads | Moisture Sensitivity Level |
|--|---------|-------------------|----------------------------|
| DP83846AVHC2WQ Product Data | CMOS7 | LQFP 80 Leads | 3 |
| DP83640TVVX Product Data | CMOS9T | LQFP 48 Leads | 3 |
| LP5221TM QBS Process Data | CMOS7 | WCP 20Bumps | 1 |
| DP83851DVN QBS Package Data | CMOS7 | LQFP 144 Leads | 3 |
| DP83848VV (QBS Product Family Data) | CMOS9T | LQFP 48 Leads | 3 |

- QBS: Qual By Similarity – Reliability data from similar product family, wafer fab process and package may be used to support qualification

Qualification Results

Data Displayed as: Total failed / Total sample size

| Test Methods | Conditions | Product Data DP83846AVHC2WQ | Product Data DP83640TVVX | Process QBS Data LP5221TM Lot1,2,3 | Product Family Data DP83848VV | QBS Package Data DP83851DVN Lot1,2,3 |
|---------------------|--|--------------------------------|-----------------------------|--|-------------------------------------|---|
| ELFR JESD22-A108 | 125 C (48hrs) | | | 0/231 | 0/805 | 0/800 |
| HTOL JESD22-A108 | 125 C (408hrs) | | 0/77 | 0/1145 | 0/240 | 0/77 |
| ACLV JESD22-A102 | 12% C, 100% 15PSI (96hrs) | | | | | 0/60 |
| HAST JESD22-A101 | 130 C, 85% 13.3PSI (96hrs) | | | | 0/80 | 0/77 |
| TMCL JESD22-A104 | -65 C to 150 C (500cyc) | | | | | 0/120 |
| HTSL JESD22-A103 | 150 C (1000hrs) | | | | | 0/45 |
| ESDH JESD22-A114 | 1.5kOhm, 100pF Room Temp (2000V) | 0/3 | 0/3 | | 0/3 | |
| ESDC JESD22-C101 | JESD22-C101 (1000V) | 0/3 | 0/3 | | 0/3 | |
| ESDM JESD22-A115 | JESD22-A115 (300V) | 0/3 | 0/3 | | 0/3 | |
| LUPS | Over Voltage and Current Test (28 C / 85 C) | 0/6 | 0/6 | | 0/6 | |

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|--------------|--|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| Japan | PCNJapanContact@list.ti.com |